

Instruction for Use
NSPACK, YSPACK, HSPACK, and YSSOCKET

1. Temperature of IC package will rise during emulation test. This may cause null function in IC package. Cool NSPACK, IC package, and HSPACK assembly with an electric fan to recover its function.
NSPACK, YSPACK, HSPACK, and YSSOCKET were developed for development and emulation test. Therefore, these connectors and socket should not be used in the final products that will be parked in the market place, and are not satisfactory for domestic electrical safety rules or EMI requirements. _Tet.htm
2. Make it sure whether your IC package can be installed on NSPACK that you are going to use. Regarding the applicable package dimensions, refer to the product catalog.
3. Hold NSPACK, YSPACK, or HSPACK by hand when you take it out of an individual box. Then remove packing materials.
4. Packing boxes will be damaged when the boxes are kept under the room temperature more than 50 degree Celsius for long time. So, stock them under the room temperature lower than 40 degree Celsius and no sunlight will reach to the stocking place.
5. Check if any burrs appear on each corner of IC package. If any burrs are found, remove them with a knife before installing the package on NSPACK.
6. Check if any IC package leads are damaged every time when you install it on NSPACK since the leads are fragile and easily damaged after a few times of installation and extraction of the package.
7. Screw NSPACK, YSPACK, or HSPACK loosely first with the driver attached or a torque driver, then tightly fasten them. Tightening torque should be 0.054N·m (0.55 kgf·cm) and should be as equal as possible on each screw. If tightened strongly one screw only, open contact problem may cause between IC leads and the socket contacts.
8. Lead pins of YSPACK can be damaged from twisting or shaking force when extracting YSSOCKET from YSPACK. Therefore, YSSOCKET should be extracted from YSPACK little by little at four corners with a (-) driver.
9. Two mounting holes of 2.3 mm diameter must be drilled to fix YSPACK onto PCB. The place underneath the screw head of 3.8 mm diameter is wiring restriction area.
10. Cover NSPACK with HSPACK when soldering NSPACK to prevent it from vaporizing flux.
Recommending soldering temperature profile:
 - Reflow 260 degree Celsius for 10 seconds max.
 - Manual 350 degree Celsius for 5 seconds max./leadHeat air soldering is also recommendable.
11. Do not clean NSPACK, YSPACK, HSPACK, or YSSOCKET since cleaning solvent will remain in the connectors.
12. IC package could not be placed in between NSPACK and YSPACK.
13. NSPACK, IC package, and HSPACK assembly is for emulation test application.
14. NSPACK, YSPACK, HSPACK, and YSSOCKET could not be used under vibration or shocking environment.

